Information and Control Korea TC Chapter

Meeting Summary and Minutes

Korea Standards Spring Meetings
Thursday, April 23, 2026
3:00 PM – 5:00 PM (KST)
SEMI Korea office, Seoul / OVTCCM (hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

October 29, 2026, OVTCCM.

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Chulhong Ahn (SK hynix), Hyungsu Kim (Doople), Kelvin Lee (Lam Research)
SEMI Staff: Natalie Shim, Cindy Bae (SEMI)

Company	*Last*	*First*	*Company*	*Last*	*First*
Doople	Kim	Hyungsu	*Samsung Electronics*	*Huh*	*Juhyuk*
Edwards High Vacuum	*Stammers*	*Peter*	*SCREEN*	*Nishimura*	*Takayuki*
Hitachi High-Tech	*Toyoshima*	*Yuko*	SEMI Korea	Bae	Cindy
KCTech	Shim	Jongsub	SEMI Korea	Shim	Natalie
Kokusai Electric	*Matsuda*	*Mitsuhiro*	SK hynix	Ahn	Chulhong
KSIA	*Seong*	*Jihye*	SK hynix	Kim	Taeseong
Linkgenesis	Chung	MinGyu	*Tokyo Electron Limited*	*Im*	*ByoungMin*
Miracom	Lim	Youngshin	*Tokyo Electron Limited*	*Yamaguchi*	*Kazutaka*
PDF Solutions	Ryu	Jong ha	Vamos AI	Kim	Charlie
PDF Solutions	*Kim*	*Anderson*	*Wonik IPS*	*Jung*	*JiKook*
Samsung Electronics	Choi	Jinhyeok	*Wonik IPS*	*Kim*	*Sehoon*
Samsung Electronics	Yoon	Junghoon	*Wonik IPS*	*Park*	*Jungjin*

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
None		

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
None	

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.
Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:
http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
None			

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
2026-0423-1	SEMI Korea	Check the status of Doc. 7422 and doc. 7422A and share updates with the Korea TC members

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
2025-1127-1	SEMI Korea	Share the information regarding SEMI Traceability Phase 0 Activity with the Korea TC members

1 Welcome, Reminders, and Introductions

Chulhong Ahn (SK hynix) called the meeting to order at 3 PM. The meeting reminders on antitrust issues, intellectual property issues, and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 1. Required Meeting Elements March 2024

2. Agenda_I&C TC_April 23_2026

2 Review of Previous Meeting Minutes

Motion: Approve the minutes as written
By / 2nd: Hyungsu Kim (Doople) / MinGyu Chung (Linkgenesis)
Discussion: None
Vote: 17-Y 0-N. Motion passed.

Attachment: 3. I&C TC Meeting Minutes_November 27_2025_v2

3 Liaison Reports

3.1 *I&C China TC Chapter*

Natalie Shim (SEMI Korea) reported for the I&C China TC Chapter. Of note:

3.1.1 Meeting Information

- Last Meeting: April 8, Hybrid
- Next Meeting: Date to be decided

3.1.2 Ballot Results

- Doc. 7139 — Line Item Revisions to E40-1218, Standard for Processing Management and E40.1-1218, Specification for SECS-II Protocol for Processing Management — passed with a technical change.
- Doc. 7140 — Line Item Revisions to E94-0819R, Specification for Control Job Management and E94.1-0819R, Specification for SECS-II Protocol for Control Job Management (CJM) — passed with a technical change.

3.1.3 Please find the attached file for details of TF activities.

Attachment: 4. China I&C Committee Chapter Liaison Report - April. 2026 v1

3.2 *I&C Japan TC Chapter*

Mitsuhiro Matsuda (Kokusai Electric) reported for the I&C Japan TC Chapter. Of note:

3.2.1 Meeting Information

- Last Meeting: April 17, SEMI Japan Office / OVTCCM (hybrid)
- Next Meeting: June 17, SEMI Japan Office / OVTCCM (hybrid)

3.2.2 Ratification Ballot Results

- Doc. R7354 — Revision to SEMI E170.1-0520 Specification For SECS-II Protocol for Secured Foundation of Recipe Management System — passed the ratification ballot and will be submitted to SEMI publication.

3.2.3 Please find the attached file for details of TF activities.

Attachment: 5. JA_I&C_Liaison_2026_Apr

3.3 *North America TC Chapter*

Natalie Shim (SEMI Korea) reported for the North America TC Chapter. Of note:

3.3.1 Meeting Information

- Last Meeting: February 11, Online via Web Conference
- Next Meeting: May 13, at ASMC

3.3.2 Leadership Changes

3.3.2.1 Fab & Equipment Computer and Device Security (CDS) TF

- Ryan Bond(Intel) stepped down from the leader. Mike Tanori (Intel) was appointed as a co-leader.

3.3.3 Ballot Results

- Doc. 7345A — Line Item Revision to SEMI E90-0624 - Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking — 1 line item (LI-1) failed and 1 line item (LI-2) passed as balloted.
- Doc. 7419 — Line-Item Revision to SEMI E120-1225 Specification for the Common Equipment Model (CEM), SEMI E120.2-1225 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1225 Specification for Equipment Self Description (EqSD), SEMI E125.2-1225 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1225 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1225 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-1225 Specification for Data Collection Management, SEMI E134.2-1225 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1225 Specification for Protocol Buffers Common Components — 2 line items (LI-1, LI-3) failed and 1 line item (LI-2) passed with editorial changes.
- Doc. 7420 — Line Item Revision to SEMI E190.1-1124 Specification for Common Data for Etch Components

  — 2 line items (LI-1, LI-2) failed.
- Doc. 7422 — Revision to SEMI E164-1224 Specification for EDA Common Metadata and to Add New Subordinate Standards, Specification for GEM Common EDA Metadata, Specification for Process Job Management GEM Common EDA Metadata, and Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata failed.
- Doc. 7425 — Line-Item Revision to SEMI E116-0324 Specification for Equipment Performance Tracking — 1 line item (LI-1) passed as balloted.

- Doc. 7428 — Revision to Add a New Subordinate Standard, Specification for Secure High-Speed SECS Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services — failed.

3.3.4 Activities Authorized by GCS between Meetings

3.3.4.1 1 SNARF was approved.

- Doc. 7422 — Revision to SEMI E164-1224 Specification for EDA Common Metadata and to Add New Subordinate Standards, Specification for GEM Common EDA Metadata, Specification for Process Job Management GEM Common EDA Metadata, and Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata

3.3.4.2 2 Ballots were authorized to proceed in cycle 4, 2026.

- Doc. 7456 — Revision to Add a New Subordinate Standard, Specification for Common Data for Deposition Components to Specification for Equipment Data Publication
- Doc. 7457 — Revision to Add a New Subordinate Standard, Specification for Common Data for Ion Implant Components to Specification for Equipment Data Publication

3.3.5 Authorized Activities

3.3.5.1 6 SNARFS were approved.

- Doc. 7447 — Line-Item Revision to SEMI E40-0324 Specification for Processing Management
- Doc. 7448 — Line-Item Revision to SEMI E175-1116 Specification for Subsystem Energy Saving Mode Communication (SESMC)
- Doc. 7449 — Line-Item Revision to SEMI E95-1101 (Reapproved 0307) Specification for Human Interface for Semiconductor Manufacturing Equipment
- Doc. 7450 — Reapproval of SEMI E173-0721 Specification for XML SECS-II Message Notation (SMN)
- Doc. 7451 — Reapproval of SEMI E54.11-0316 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices
- Doc. 7452 — Reapproval of SEMI E54.3-0698 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device

3.3.6 Authorized Ballots

3.3.6.1 18 Ballots were authorized to proceed in cycle 4, 2026.

- Doc. 7070 — Revision to Add a New Subordinate Standard, Specification for Common Data for Vacuum Components to Specification for Equipment Data Publication
- Doc. 7187 — Revision to SEMI E167-1213 Specification for Equipment Energy Saving Mode Communications (EESM) and SEMI E167.1-1213 Specification for SECS-II Protocol for Equipment Energy Saving Mode Communications
- Doc. 7354B — Line Item Revision to SEMI E90-0624 Specification for Substrate Tracking and SEMI E90.1-0624 - Specification for SECS-II Protocol Substrate Tracking
- Doc. 7380A — Line Item Revision to SEMI E142-0225 Specification for Substrate Mapping, SEMI E142.1-0225 Specification for XML Schema for Substrate Mapping, SEMI E142.2-1016 (0225) Specification for SECS II Protocol for Substrate Mapping, SEMI E142.3-1016 (0225) Specification for Web Services for Substrate Mapping, SEMI E142.4-1022 (0225) Specification for SECS II Protocol for Substrate Mapping Using Item Transfer
- Doc. 7381 — Revision to Add a New Subordinate Standard, Specification for Transforming Non-E142 XY Coordinates to SEMI E142-0125: Specification for Substrate Mapping

- Doc. 7419A — Line-Item Revision to SEMI E120-1225 Specification for the Common Equipment Model (CEM), SEMI E120.2-1225 Specification for Protocol Buffers for Common Equipment Model (CEM), SEMI E125-1225 Specification for Equipment Self Description (EqSD), SEMI E125.2-1225 Specification for Protocol Buffers for Equipment Self Description (EqSD), SEMI E132-1225 Specification for Equipment Client Authentication and Authorization, SEMI E132.2-1225 Specification for Protocol Buffers for Equipment Client Authentication and Authorization (ECA), SEMI E134-1225 Specification for Data Collection Management, SEMI E134.2-1225 Specification for Protocol Buffers of Data Collection Management, and SEMI E179-1225 Specification for Protocol Buffers Common Components
- Doc. 7420A — Line Item Revision to SEMI E190.1-1124 Specification for Common Data for Etch Components
- Doc. 7422A — Revision to SEMI E164-1224 Specification for EDA Common Metadata and to Add New Subordinate Standards, Specification for GEM Common EDA Metadata, Specification for Process Job Management GEM Common EDA Metadata, and Specification for Carrier Management Services Common EDA Metadata to SEMI E164-1224 Specification for EDA Common Metadata
- Doc. 7426 — Line-Item Revision to SEMI E191-1024 Specification for Computing Device Cybersecurity Status Reporting, and SEMI E191.1-1024 Specification for SECS-II Protocol for Computing Device Cybersecurity Status Reporting
- Doc. 7427 — Line Item Revision to SEMI E172-0725 Specification for SECS Equipment Data Dictionary (SEDD)
- Doc. 7428A — Revision to Add a New Subordinate Standard: Specification for Secure High-Speed Secs Message Service (Secure-HSMS) to SEMI E37-0222 Specification for High-Speed SECS Message Services (HSMS) Generic Services
- Doc. 7447 — Line Item Revision to SEMI E40-0324 Specification for Processing Management
- Doc. 7448 — Reapproval of SEMI E173-0721 Specification for XML SECS-II Message Notation (SMN)
- Doc. 7449 — Line Item Revision to SEMI E175-1116 Specification for Subsystem Energy Saving Mode Communication (SESMC)
- Doc. 7451 — Reapproval of SEMI E54.11-0316 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices
- Doc. 7452 — Reapproval of SEMI E54.3-0698 (Reapproved 0721) Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device
- Doc. 7456 — Revision to Add a New Subordinate Standard, Specification for Common Data for Deposition Components to Specification for Equipment Data Publication
- Doc. 7457 — Revision to Add a New Subordinate Standard, Specification for Common Data for Ion Implant Components to Specification for Equipment Data Publication

3.3.7 5-Year Review

- SEMI E54. 11-0316 (Reapproved 0721) — Specification for Sensor/Actuator Network Specific Device Model for Endpoint Devices
- SEMI E54.3-0698 (Reapproved 0721) — Specification for Sensor/Actuator Network Specific Device Model for Mass Flow Device
- SEMI E173-0721 — Specification for XML SECS-II Message Notation (SMN)

3.3.8 SNARF activity of Digital Twins in Manufacturing Task Force was also shared and discussed.

3.3.9 Please find the attached file for details of TF activities.

Attachment: 6. NA IC Liaison Report 2026

3.4 *I&C Taiwan TC Chapter*

Natalie Shim (SEMI Korea) reported for the Taiwan TC Chapter. Of note:

3.4.1 Meeting Information

- Last Meeting: June 12, 2025 / OVTCCM
- Next Meeting: Date to be decided

3.4.2 Leadership Changes

3.4.2.1 Equipment Edge Data Governance TF

- Ya Chi Tu (TSMC) was appointed as co-leader.

3.4.3 Ballot Results

- Doc. 6938C — New Standard, Guide for Equipment Edge Data Governance — passed with editorial changes, and will be forwarded to ISC A&R.

3.4.4 Authorized Activities

- TC Chapter approved Ya Chi Tu (TSMC) to be co-leader of Equipment Edge Data Governance TF.

3.4.5 SNARF(s) Abolished

- Doc. 7103 — Line Item Revision to SEMI E187(0122) Specification for Cybersecurity of Fab Equipment

3.4.6 Please find the attached file for details of TF activities.

Attachment: 7. IC Taiwan Liaison Report_20250612_V1

3.5 *SEMI Staff Report*

Natalie Shim (SEMI Korea) gave the SEMI Staff Report. Of note:

3.5.1 SEMICON Upcoming Events

- SEMIEXPO Heartland, April 29-30, Detroit
- SEMICON Southeast Asia, May 5-7, Kuala Lumpur
- SEMICON Taiwan, September 2-4, Taipei
- SEMICON India, September 17-19, New Delhi

3.5.2 Upcoming NA Meetings 2026

- NA Spring Meeting on May 11 to 14 at Hilton Albany, New York, in conjunction with ASMC
- SEMICON West Meeting on October 12 to 15 at San Francisco

3.5.3 Critical Dates for SEMI Standards Ballots

- See https://www.semi.org/en/Standards/Ballots

3.5.4 SEMI Advanced Semiconductor Manufacturing Conference (ASMC)

- ASMC 2026 will be held on May 11 to 14 at Hilton Albany, New York. It is SEMI's international technical conference for discussing solutions that improve the collective manufacturing expertise of the semiconductor industry. The conference will provide a platform for semiconductor professionals to network and learn the latest in the practical application of advanced manufacturing strategies and methodologies.

3.5.5 All SEMI Standards Task Forces shall use Connected@SEMI for managing TF activities and storing documents.

Attachment: 8. Staff_HQ Report Feb 2026 v3_ns

4 Ballot Review

None

5 Subcommittee and Task Force Reports

5.1 *GEM 300 TF*

- There was no update from the TF.

5.2 *Diagnostic Data Acquisition (DDA) TF*

- Hyungsu Kim (Doople) gave a report on ballot activities of NA DDA TF.

5.3 *Advanced Back-End Factory Integration (ABFI) TF*

- Hyungsu Kim (Doople) shared an update on discussions regarding standardization item for back-end factories. The TF is developing the data structure for tracking the lifecycle from wafer to net die for a standardization item and the initial draft was shared. The structure will be further refined through ongoing discussions. Those who would like to join the discussion, please inform SEMI Korea of their interest in participating via email.

6 Old Business

None

7 New Business

7.1 *ABFI TF Ongoing Discussion on Standardization Items*

- Please refer to the Section 5.3 of this minutes.

8 Next Meeting and Adjournment

The next meeting is scheduled for Thursday, October 29, 2026, via OVTCCM. See http://www.semi.org/standards-events for the current list of events.

Adjournment: 5:00 PM.

Respectfully submitted by:

Cindy Bae

Coordinator

SEMI Korea

Phone: 82.2.531.7899

Email: sbae@semi.org

Minutes tentatively approved by:

Chul Hong Ahn (SK hynix), Co-chair	<Date approved>
Hyungsu Kim (Doople), Co-chair	<Date approved>
Kelvin Lee (Lam Research), Co-chair	<Date approved>

Table 14 Index of Available Attachments[#1]

Title	*Title*
1. Required Meeting Elements March 2024	5. JA_I&C_Liaison_2026_Apr
2. Agenda_I&C TC_April 23_2026	6. NA IC Liaison Report 2026
3. I&C TC Meeting Minutes_ November27_2025_v2	7. IC Taiwan Liaison Report_20250612_V1
4. China I&C Committee Chapter Liaison Report - April. 2026 v1	8. Staff_HQ Report Feb 2026 v3_ns

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.